

FIG. 1

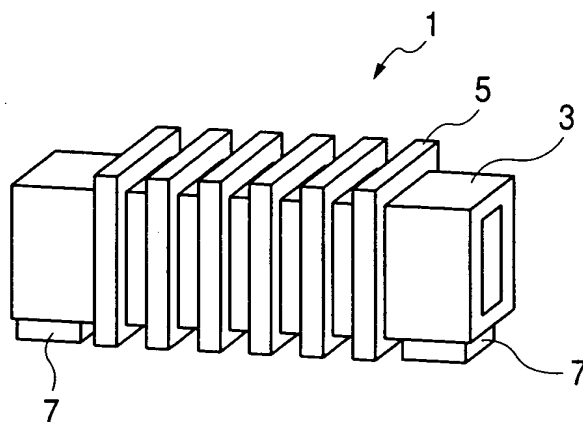
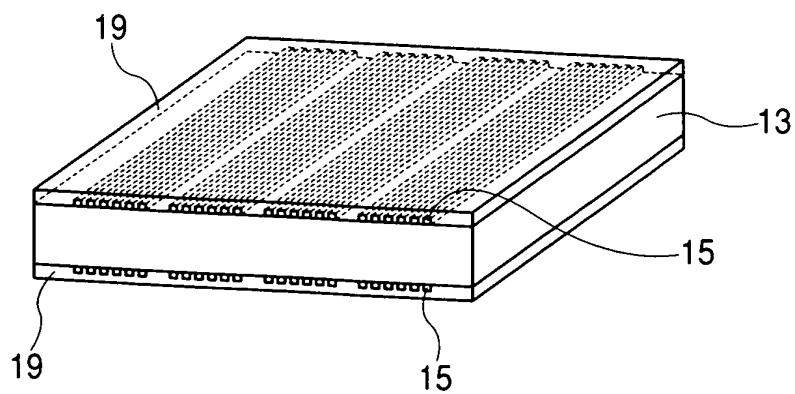


FIG. 2A



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FIG. 2B

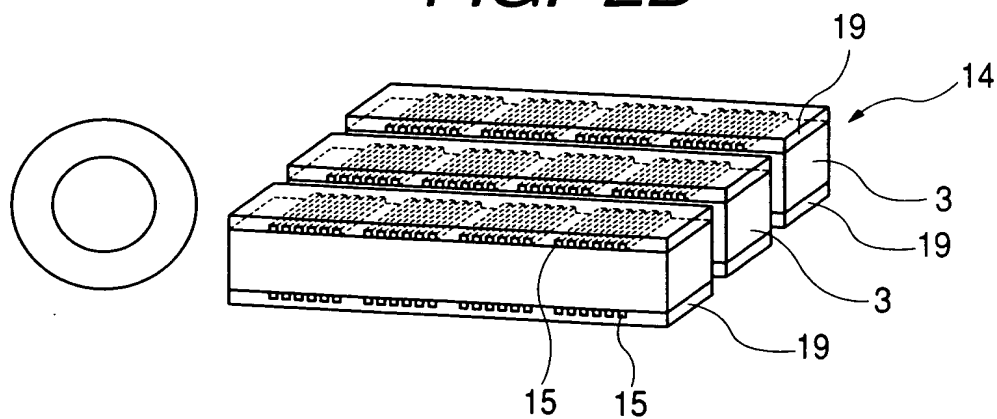


FIG. 2C

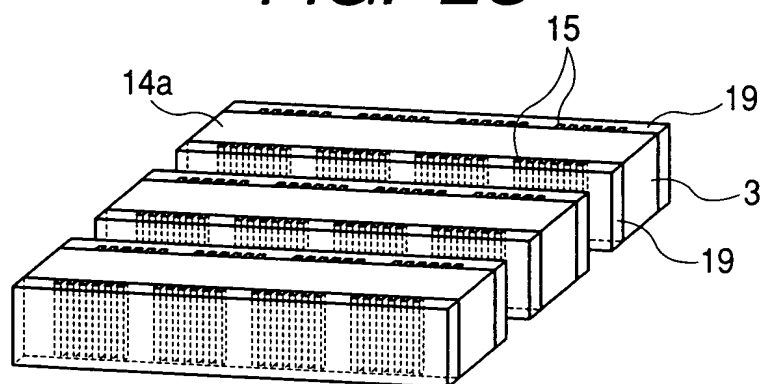
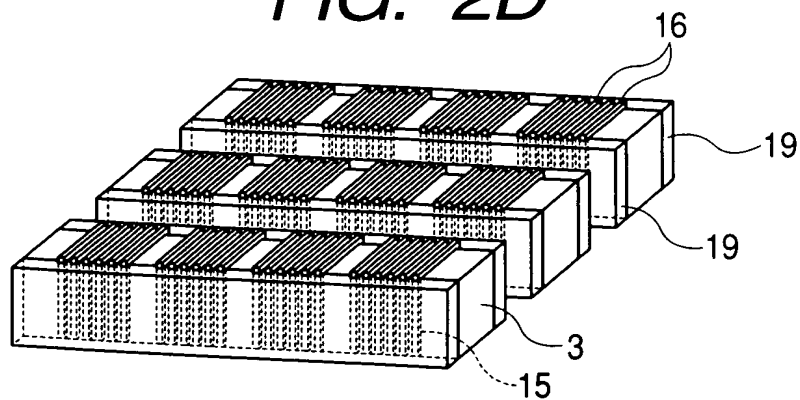


FIG. 2D



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FIG. 2E

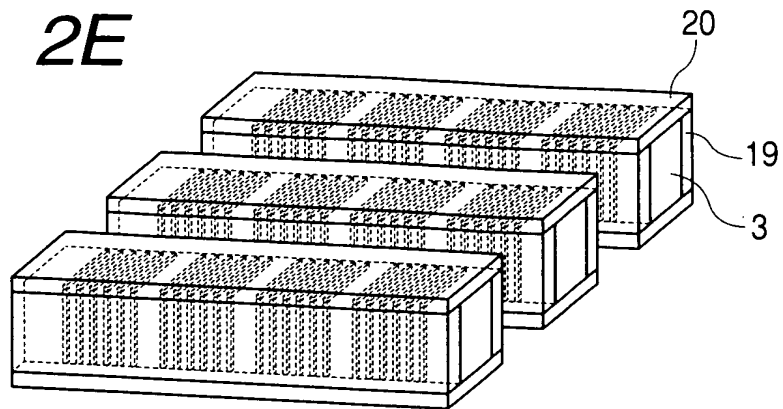


FIG. 3A

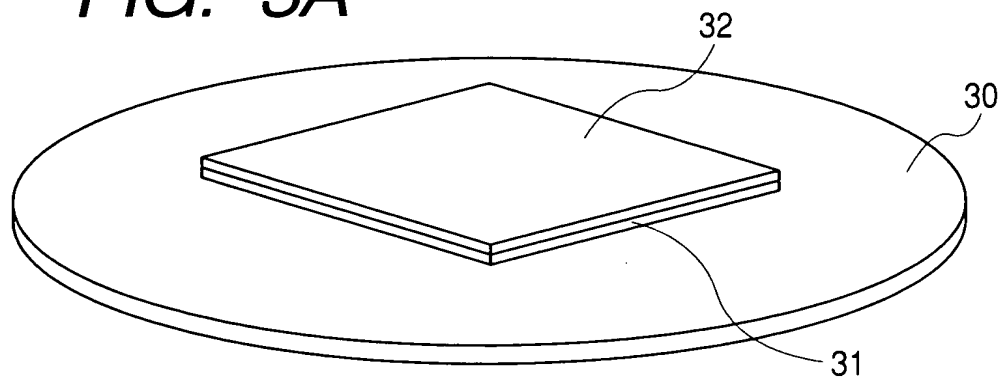


FIG. 3B

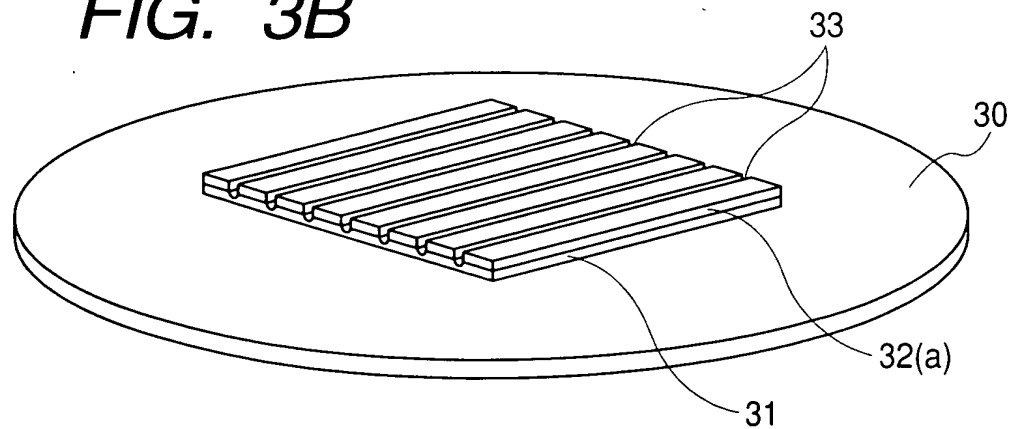
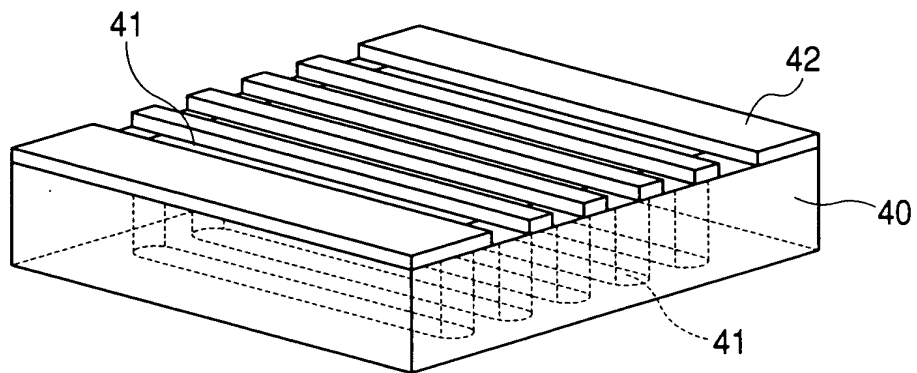


FIG. 3C



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FIG. 3D

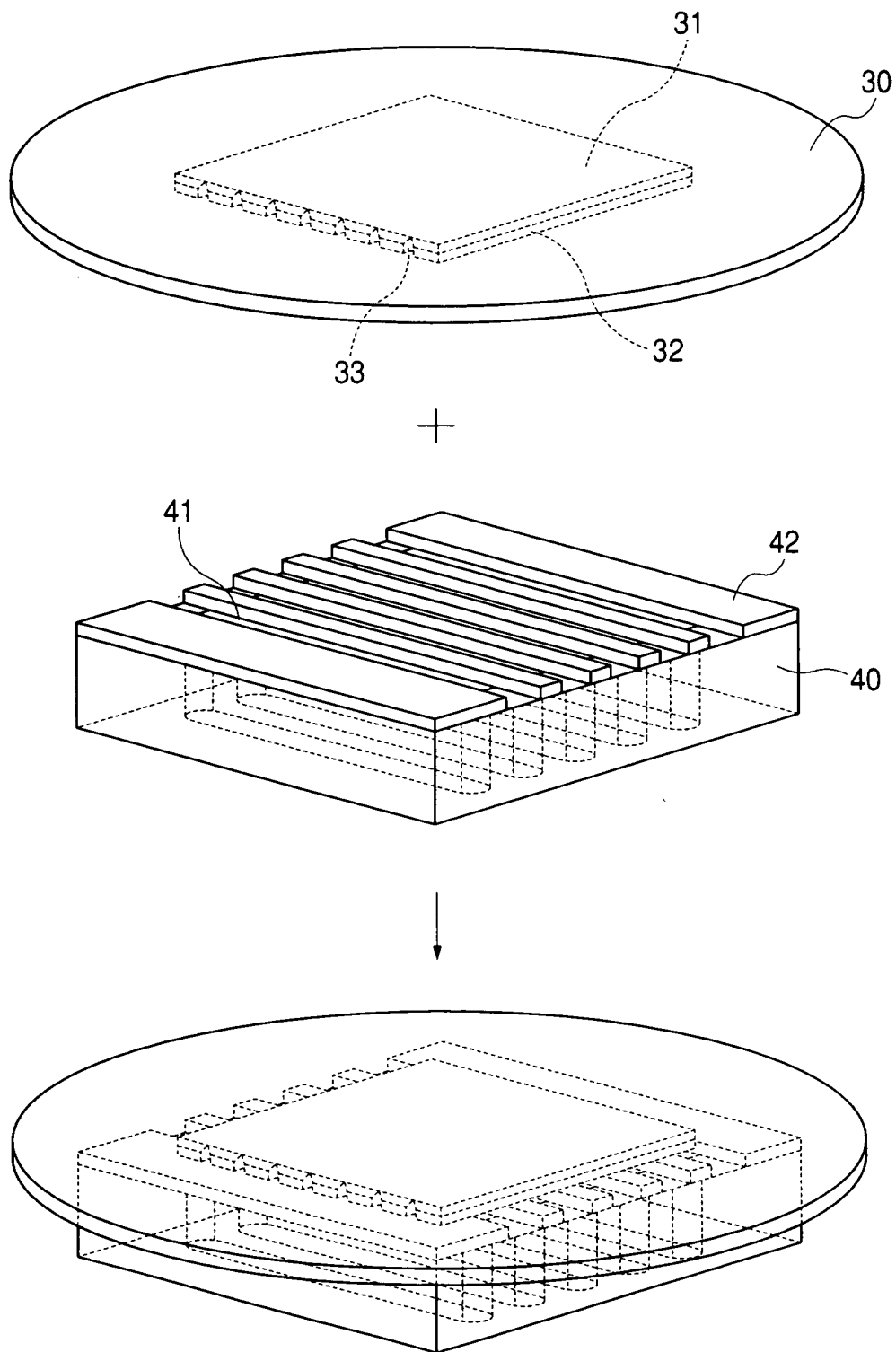


FIG. 3E

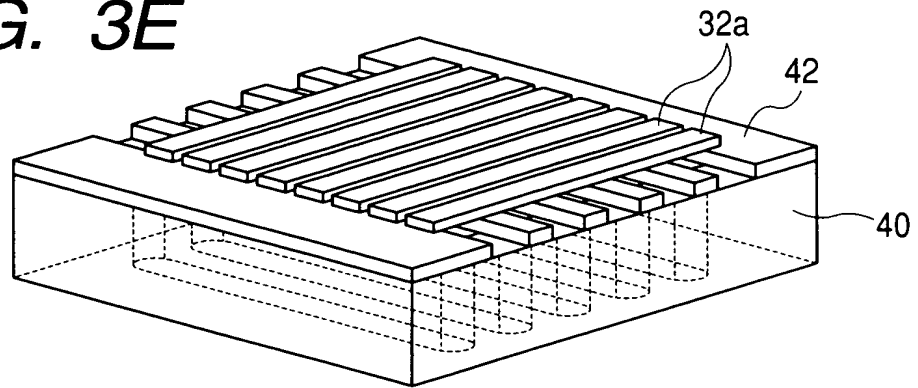


FIG. 3F

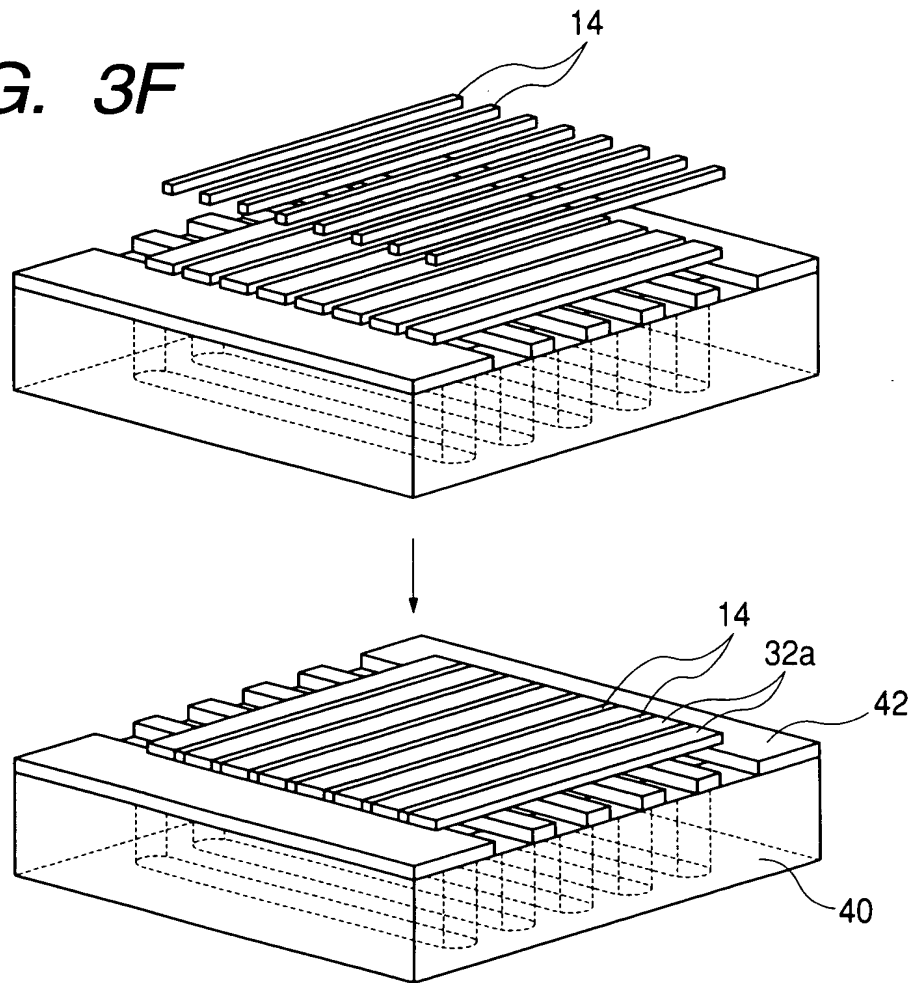


Figure 1 is a schematic diagram illustrating the assembly of a semiconductor device. The diagram shows three main components arranged vertically. The top component is a substrate 50 with a series of vertical protrusions 51. An arrow points down from the substrate 50 to a central assembly 40. The central assembly 40 consists of a base 42 with a grid of horizontal and vertical strips 43. Below this, an arrow points up to a series of vertical strips 46 mounted on a base 45. Dashed lines 41 and 32a indicate the alignment and connection of the strips 43 to the strips 46.

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FIG. 3H

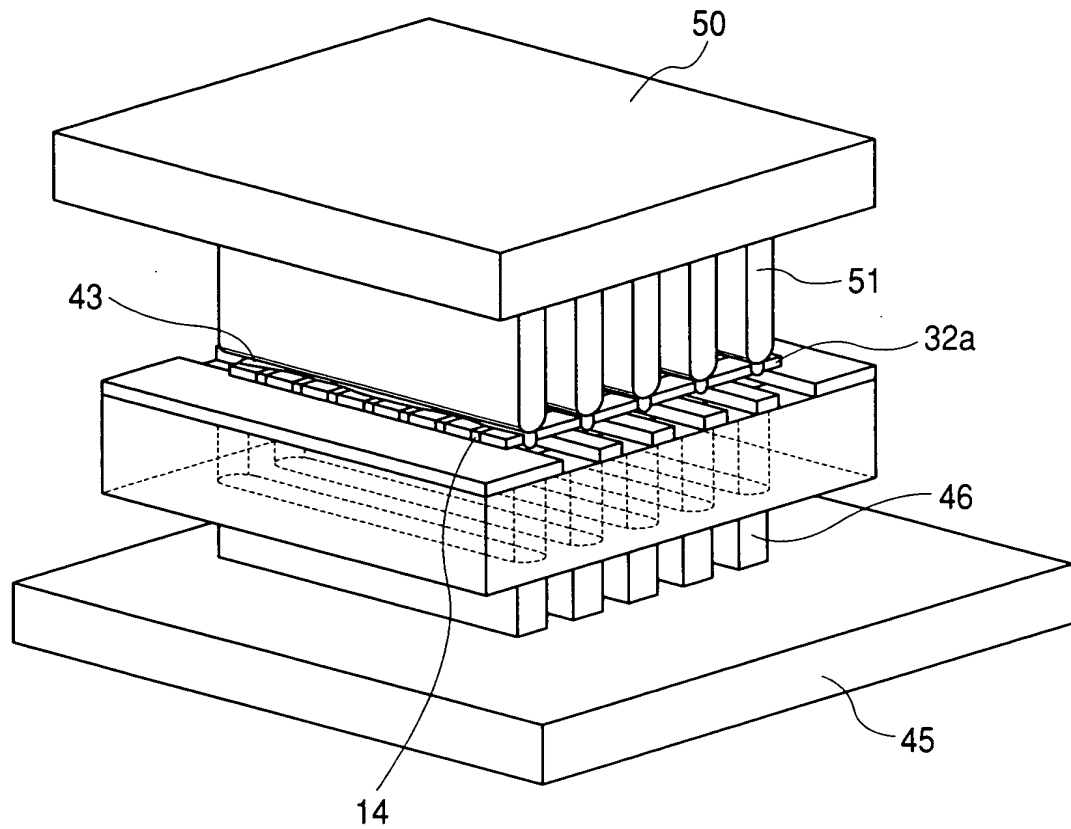


FIG. 3I

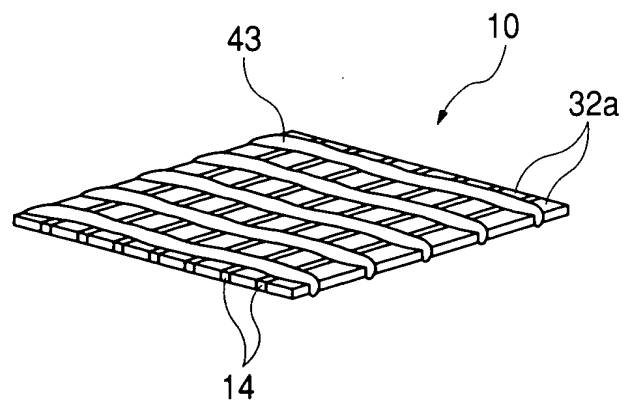


FIG. 3J

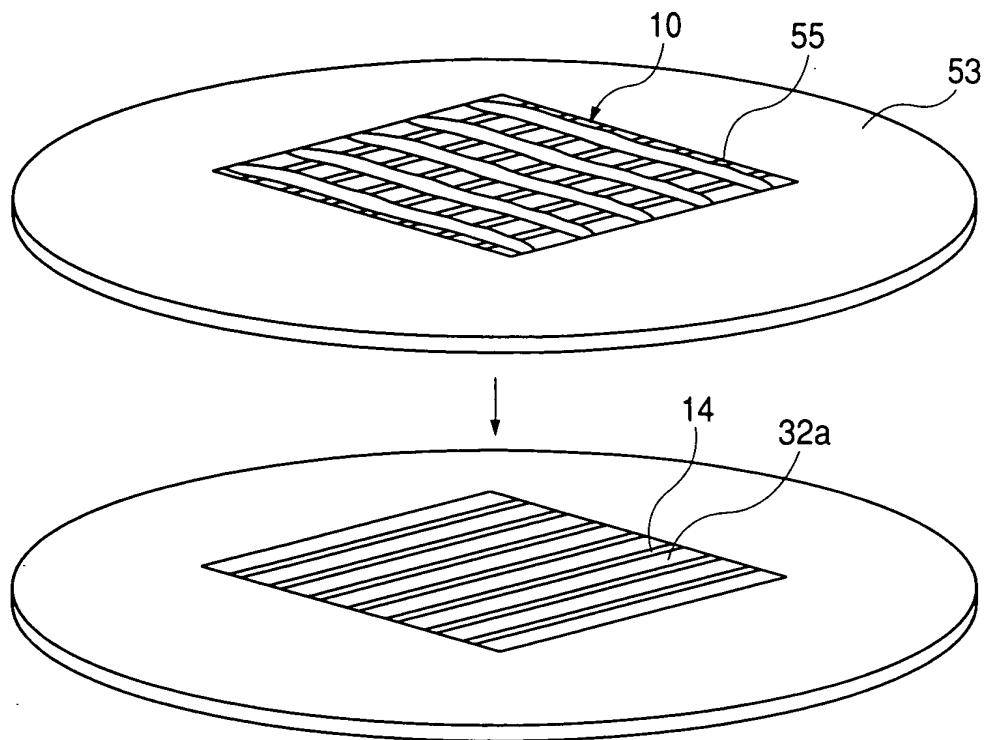


FIG. 3K

